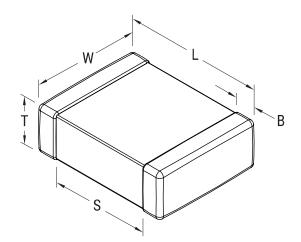


C1206X330FATAC7210

SMD Comm X8G HT150C Flex, Ceramic, 33 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

| General Information | |
|--------------------------|--|
| Series | SMD Comm X8G HT150C Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 15 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

 Dimensions

 Chip Size
 1206

 L
 3.3mm +/-0.4mm

 W
 1.6mm +/-0.35mm

 T
 0.78mm +/-0.20mm

 S
 1.5mm MIN

 B
 0.6mm +/-0.25mm

Packaging Specifications Packaging T&R

Packaging Quantity

T&R, 330mm, Plastic Tape 10000

| Specifications | |
|--|--|
| Capacitance | 33 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 1% |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 625 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

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